



# Product data sheet

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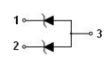








SOT - 23



# AZ23C2V7-AZ23C39 ZENER DIODE

#### FEATURES

- Dual zeners in common anode configuration.
- 300mW power dissipation rating.
- Ideally suited for automatic insertion.
- $\triangle$ Vz for both diodes in one case is  $\leq$ 5%.
- Common cathode style available see DZ series.
- Also available in lead free version.

#### Maximum Ratings(T₂=25℃ unless otherwise specified)

Characteristic		Symbol	Value	Unit
Forward Voltage	@ I <sub>F</sub> = 10mA	V <sub>F</sub>	0.9	V
Power Dissipation		PD	300	mW
Thermal Resistance from Junction to Ambient		$R_{ extsf{ heta}JA}$	417	°C/W
Operation Junction and Storage Temperature Range		$T_J, T_{STG}$	-55~+150	°C





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## **ELECTRICAL CHARACTERISTICS**

### T<sub>a</sub>=25℃ unless otherwise specified

Type Marking Number Code		Zener Voltage Range (note1)	Maximum Zener Impedance (note 2)		Typical Temperature Coefficient	Min Reverse Voltage (note1)
		@ I <sub>ZT</sub> =5.0mA	Z <sub>ZT</sub> @I <sub>ZT</sub> =5.0mA	Z <sub>Zk</sub> @I <sub>Zk</sub> =1.0mA	Coemcient	@I <sub>R</sub> =0.1 μA
		V <sub>Z</sub> (V )	Ω	Ω	Tc (%/℃Ł	V <sub>R</sub> (V)
AZ23C2V7	KD1	2.5-2.9	83	500	-0.065	—
AZ23C3V0	KD2	2.8-3.2	95	500	-0.060	—
AZ23C3V3	KD3	3.1-3.5	95	500	-0.055	—
AZ23C3V6	KD4	3.4-3.8	95	500	-0.055	—
AZ23C3V9	KD5	3.7-4.1	95	500	-0.050	—
AZ23C4V3	KD6	4.0-4.6	95	500	-0.035	—
AZ23C4V7	KD7	4.4-5.0	78	500	-0.015	—
AZ23C5V1	KD8	4.8-5.4	60	480	+0.005	0.8
AZ23C5V6	KD9	5.2-6.0	40	400	+0.020	1.0
AZ23C6V2	KDA	5.8-6.6	10	200	+0.030	2.0
AZ23C6V8	KDB	6.4-7.2	8.0	150	+0.045	3.0
AZ23C7V5	KDC	7.0-7.9	7.0	50	+0.050	5.0
AZ23C8V2	KDD	7.7-8.7	7.0	50	+0.055	6.0
AZ23C9V1	KDE	8.5-9.6	10	50	+0.065	7.0
AZ23C10	KDF	9.4-10.6	15	70	+0.065	7.5
AZ23C11	KDG	10.4-11.6	20	70	+0.070	8.5
AZ23C12	KDH	11.4-12.7	20	90	+0.075	9.0
AZ23C13	KDI	12.4-14.1	25	110	+0.080	10.0
AZ23C15	KDJ	13.8-15.6	30	110	+0.080	11.0
AZ23C16	KDK	15.3-17.1	40	170	+0.090	12.0
AZ23C18	KDL	16.8-19.1	50	170	+0.090	14.0
AZ23C20	KDM	18.8-21.2	50	220	+0.090	15.0
AZ23C22	KDN	20.8-23.3	55	220	+0.090	17.0
AZ23C24	KDO	22.8-25.6	80	220	+0.090	18.0
AZ23C27	KDP	25.1-28.9	80	250	+0.090	20.0
AZ23C30	KDQ	28-32	80	250	+0.090	22.5
AZ23C33	KDR	31-35	80	250	+0.090	25.0
AZ23C36	KDS	34-38	90	250	+0.090	27.0
AZ23C39	KDT	37-41	90	300	+0.110	29.0

Notes: 1. Short duration test pulse used to minimize self-heating effect.

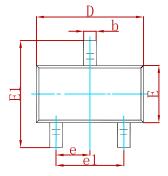
2. f=1kHz

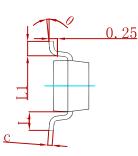


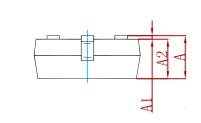


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## PACKAGE MECHANICAL DATA

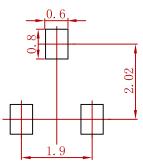






Cumph of	Dimensions In Millimeters		Dimensions In Inches	
Symbol	Min	Max	Min	Max
А	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
с	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
е	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

### Suggested Pad Layout



Note:

Controlling dimension:in millimeters.
General tolerance:± 0.05mm.
The pad layout is for reference purposes only.

#### **REEL SPECIFICATION**

P/N	PKG	QTY
AZ23C2V7-AZ23C39	SOT-23	3000





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